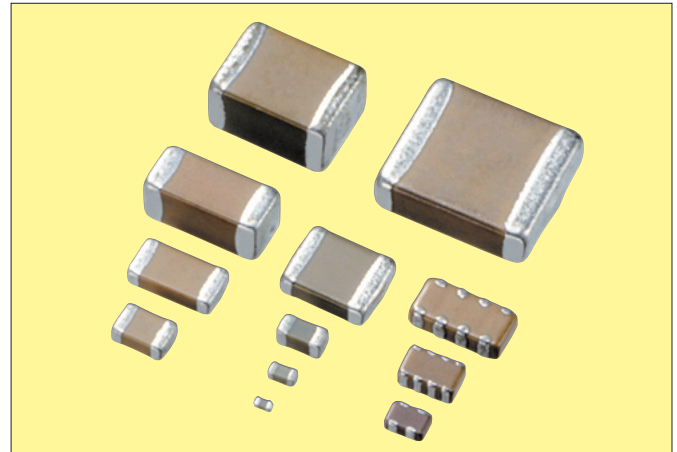


Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications, including general-purpose CM series, high-voltage CF series, low profile CT series, and DM series for automotive uses.

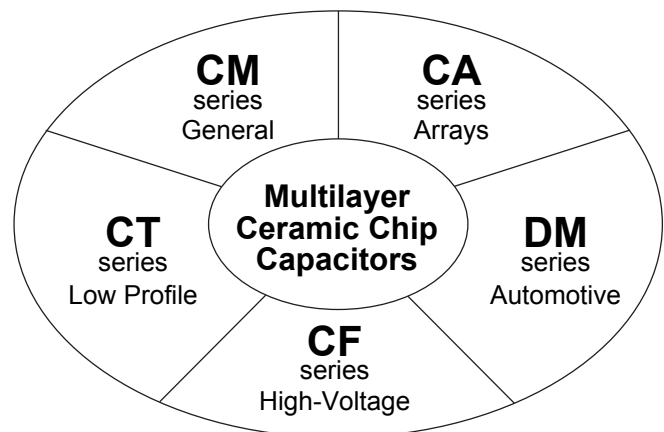
Features

- We have factories worldwide in order to supply our global customer bases quickly and efficiently and to maintain our reputation as one of the highest-volume producers in the industry.
- All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- By combining superior manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications.
- Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and super quality.
- Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.

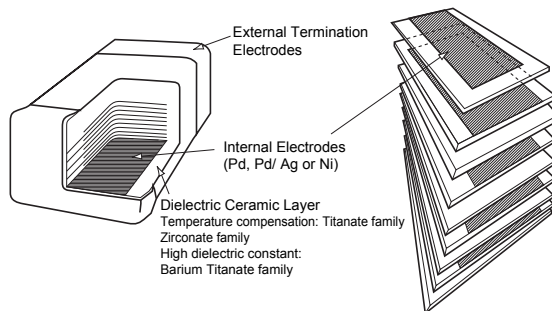


Pb Free

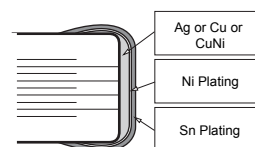
RoHS Compliant



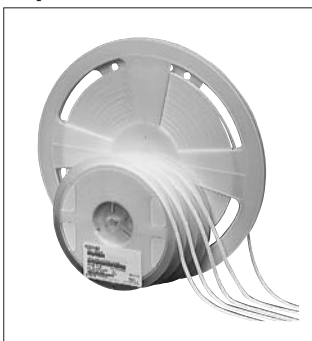
Structure



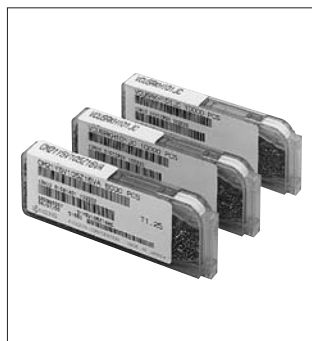
Nickel Barrier Termination Products



Tape and Reel



Bulk Cassette



Please contact your local AVX, Kyocera sales office or distributor for specifications not covered in this catalog.

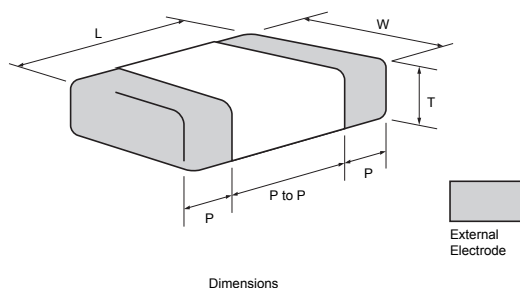
Our products are continually being improved. As a result, the capacitance range of each series is subject to change without notice. Please contact an sales representative to confirm compatibility with your application.

Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

Series	Dielectric Options	Typical Applications	Features	Terminations	Available Size
CM	C0G (NP0) X5R X7R *X6S *X7S Y5V	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
CT	C0G (NP0) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
DM	X7R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CA	C0G (NP0) X5R, X7R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508

* option

Dimensions



Dimensions

Tape & Reel

Size	EIA CODE	JIS CODE	Dimensions (mm)					
			L	W	P min.	P max.	P to P min.	T max.
03	0201	0603	0.6±0.03	0.3±0.03	0.13	0.23	0.20	0.33
05	0402	1005	1.0±0.05	0.5±0.05	0.15	0.35	0.30	0.55
105	0603	1608	1.6±0.10	0.8±0.10	0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.00
52	2208	5720	5.7±0.40	2.00±0.20	0.15	0.85	4.20	2.20
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

- T (Thickness) depends on capacitance value.
Standard thickness is shown on the appropriate product pages.
- CA series (please refer applicable page)

Bulk Cassette

Size	EIA CODE	JIS CODE	L	W	T	P		P to P
						min.	max.	min.
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50
21	0805	2012	2.0±0.1	1.25±0.1	1.25±0.1	0.20	0.75	0.70

Note) Regarding support for Bulk cases, please contact us for further information.

Multilayer Ceramic Chip Capacitors Ordering Information



KYOCERA PART NUMBER:

CM 21 X7R 104 K 50 A T □ □ □

SERIES CODE

CM = General Purpose CA = Capacitor Arrays
CF = High Voltage
CT = Low Profile
DM = Automotive

SIZE CODE

SIZE	EIA (JIS)	SIZE	EIA (JIS)	SIZE	EIA (JIS)
03	= 0201 (0603)	21	= 0805 (2012)	52	= 2208 (5720)
05	= 0402 (1005)	316	= 1206 (3216)	55	= 2220 (5750)
105	= 0603 (1608)	32	= 1210 (3225)	D11	= 0405 (1012)/ 2cap
F12	= 0508 (1220)/ 4cap	42	= 1808 (4520)	D12	= 0508 (1220)/ 2cap
		43	= 1812 (4532)		

DIELECTRIC CODE

CODE EIA CODE
CG = C0G (NPO) X7S = X7S (Option)
X5R = X5R X6S = X6S (Option)
X7R = X7R Y5V = Y5V

Negative dielectric types are available on request.

CAPACITANCE CODE

Capacitance expressed in pF. 2 significant digits plus number of zeros.

For Values < 10pF, Letter R denotes decimal point,

eg. 100000pF = 104 1.5pF = 1R5
0.1μF = 104 0.5pF = R50
4700pF = 472 100μF = 107

TOLERANCE CODE

A = ±0.05pF (option)	D = ±0.5pF	J = ±5%	Z = -20 to +80%
B = ±0.1pF (option)	F = ±1pF	K = ±10%	
C = ±0.25pF	G = ±2%	M = ±20%	

VOLTAGE CODE

04 = 4VDC	100 = 100VDC	1000 = 1000VDC
06 = 6.3VDC	250 = 250VDC	2000 = 2000VDC
10 = 10VDC	400 = 400VDC	3000 = 3000VDC
16 = 16VDC	630 = 630VDC	4000 = 4000VDC
25 = 25VDC		
35 = 35VDC		
50 = 50VDC		

TERMINATION CODE

A = Nickel Barrier

PACKAGING CODE

B = Bulk	L = 13" Reel Taping & 4mm Cavity pitch
C = Bulk Cassette (option)	H = 7" Reel Taping & 2mm Cavity pitch
T = 7" Reel Taping & 4mm Cavity pitch	N = 13" Reel Taping & 2mm Cavity pitch

OPTION

Thickness max. value is indicated in CT series

EX. 125 → 1.25mm max.
095 → 0.95mm max.

Multilayer Ceramic Chip Capacitors

Temperature Characteristics and Tolerance



High Dielectric Constant

EIA Dielectric	Temperature Range	ΔC max.
X5R	-55 to 85°C	±15%
X7R	-55 to 125°C	
X7S	-55 to 125°C	±22%
X6S	-55 to 105°C	
Y5V	-30 to 85°C	-82 to +22%

Temperature Compensation Type

Electric Code Value (pF)	C0G	UΔ N750	SL +350 to -1000
0.5 to 2.7	CK	UK	SL
3.0 to 3.9	CJ	UJ	SL
4.0 to 9.0	CH	UJ	SL
≥10	CG	UJ	SL

K = ±250ppm/°C, J = ±120ppm/°C, H = ±60ppm/°C, G = ±30ppm/°C
e.g. CG = 0±30ppm/°C

Note: All parts will be marked as "CG" but will conform to the above table.

Available Tolerances

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
COG	C=±0.25pF D=±0.50pF F=±1pF	*1 <10pF
	*3 A=±0.05pF B=±0.1pF	<0.5pF ≤5pF
	G=±2% J=±5% K=±10%	≥10pF E12 Series
	*2 K=±10% M=±20%	E6 Series
X5R X6R X7R		
Y5V	Z=-20% to +80%	E3 Series

Note:

*1 Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF

*2 J = ±5% for X7R (X5R) is available on request.

*3 option

E Standard Number

E3	E6	E12	E24 (Option)	
1.0	1.0	1.0	1.0	1.1
		1.2	1.2	1.3
	1.5	1.5	1.5	1.6
		1.8	1.8	2.0
2.2	2.2	2.2	2.2	2.4
		2.7	2.7	3.0
	3.3	3.3	3.3	3.6
		3.9	3.9	4.3
4.7	4.7	4.7	4.7	5.1
		5.6	5.6	6.2
	6.8	6.8	6.8	7.5
		8.2	8.2	9.1

Features

We offer a diverse product line ranging from ultra-compact (0.6×0.3mm) to large (4.3×3.2mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

Applications

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

Temperature Compensation Dielectric

Size (EIA Code)	CM03 (0201)					CM05 (0402)			CM105 (0603)	CM21 (0805)				
Temperature Characteristics	CΔ		UΔ		SL	CΔ	UΔ	SL	CΔ	CΔ				
Rated Voltage (VDC) Capacitance (pF)	25	50	16	25	25	50	50	50	50	100	16	25	50	100
R20 0.2	A	A	A											
R50 0.5														
1R0 1.0														
1R5 1.5														
2.0														
3.0	A													
4.0														
5.0														
6.0														
7.0														
8.0	A													
9.0														
100 10														
120 12														
15 15														
18 18	A													
22 22														
27 27														
33 33														
39 39														
47 47	A													
56 56														
68 68														
82 82														
101 100														
121 120	A													
150 150														
180 180														
220 220														
270 270														
330 330	A													
390 390														
470 470														
560 560														
680 680														
820 820	A													
102 1000														
122 1200														
1500 1500														
1800 1800														
2200 2200	A													
2700 2700														
3300 3300														
3900 3900														
4700 4700														
5600 5600	A													
6800 6800														
8200 8200														
103 10000														
123 12000														
15000 15000	A													
18000 18000														

Thickness and standard package quantity

Size	*03	*05	105	*105	21, 316, 32								
Thickness (mm)	A	B	C	C	D	E	F	G	H	I	J	K	L
	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size	43			
Thickness (mm)	J	K	L	M
	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	—

Note: P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

X5R Dielectric

Size (EIA Code)	CM03 (0201)					CM05 (0402)					CM105 (0603)					CM21 (0805)							
Rated Voltage (VDC)	4	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	50	4	6.3	10	16	25	50
Capacitance (pF)																							
101	100																						
151	150																						
220																							
330																							
470																							
680																							
102	1000																						
152	1500																						
2200																							
3300																							
4700																							
6800																							
103	10000																						
153	15000																						
22000																							
33000																							
47000																							
68000																							
104	100000																						
154	150000																						
220000																							
330000																							
470000																							
680000																							
105	1000000																						
155	1500000																						
2200000																							
3300000																							
4700000																							
6800000																							
106	10000000																						
156	15000000																						
22000000																							

Size (EIA Code)	CM316 (1206)					CM32 (1210)						CM43 (1812)	
Rated Voltage (VDC) Capacitance (pF)	6.3	10	16	25	50	4	6.3	10	16	25	50	6.3	50
104 100000					F								
220000				F							H		
470000											K		
105 1000000				J									
2200000			J							H			
4700000				J					I	K			L
106 10000000	J	J	J	J				K	L	L			
22000000							L						
47000000								L					
107 100000000												M	

Optional Spec.

Thickness and standard package quantity

Size	*03	*05	105	*105	21, 316, 32								
Thickness (mm)	A	B	C	C	D	E	F	G	H	I	J	K	L
	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size	43			
Thickness (mm)	J	K	L	M
	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	—

Note: P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

X7R, Dielectric

Size (EIA Code)	CM03 (0201)			CM05 (0402)			CM105 (0603)						CM21 (0805)					
Rated Voltage (VDC) Capacitance (pF)	10	16	25	16	25	50	6.3	10	16	25	50	100	6.3	10	16	25	50	100
101 100																		
151 150		A	A															
220																		
330		A																
470																		
680																		
102 1000																		
152 1500	A																	
2200																		
3300																		
4700																		
6800																		
103 10000																		
153 15000																		
22000																		
33000																		
47000																		
68000																		
104 100000																		
154 150000																		
220000																		
330000																		
470000																		
680000																		
105 1000000																		
155 1500000																		
2200000																		
3300000																		
4700000																		
106 10000000																		

Size (EIA Code)	CM316 (1206)						CM32 (1210)					CM43 (1812)	
Rated Voltage (VDC) Capacitance (pF)	6.3	10	16	25	50	100	10	16	25	50	100	50	100
103 10000													
22000													
47000													
104 100000													
220000													
470000													
105 1000000													
2200000													
4700000													
106 10000000													
22000000													

Optional Spec.

Y5V Dielectric

Size (EIA Code)	CM03 (0201)		CM05 (0402)				CM105 (0603)				CM21 (0805)				CM316 (1206)			CM32 (1210)		
Rated Voltage (VDC) Capacitance (pF)	6.3	10	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	10	16	25
102 1000		A																		
2200																				
4700																				
103 10000	A																			
22000																				
47000																				
104 100000																				
220000																				
470000																				
105 1000000																				
2200000																				
4700000																				
106 10000000																				
22000000																				
47000000																				

Thickness and standard package quantity

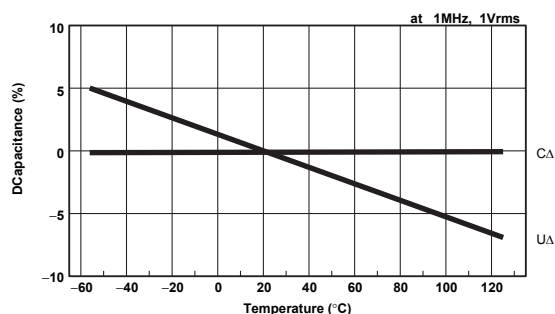
Size	*03	*05	105	*105	21, 316, 32								
Thickness (mm)	A	B	C	C	D	E	F	G	H	I	J	K	L
	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2.5kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size	43			
Thickness (mm)	J	K	L	M
	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	—

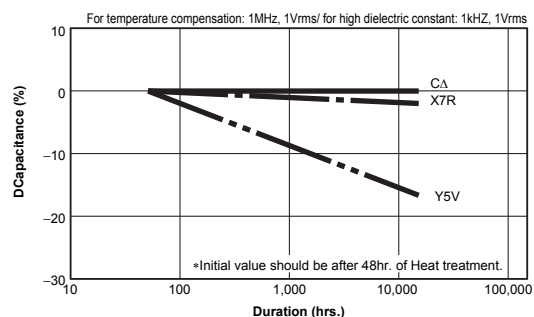
Note: P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

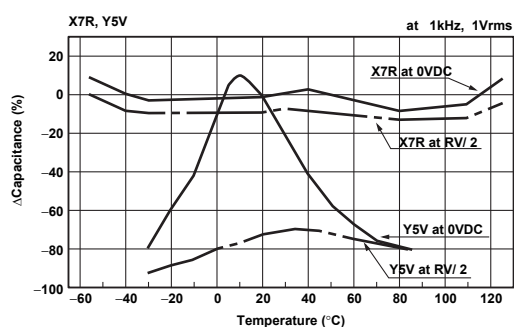
Capacitance-Temperature
(temperature compensation)



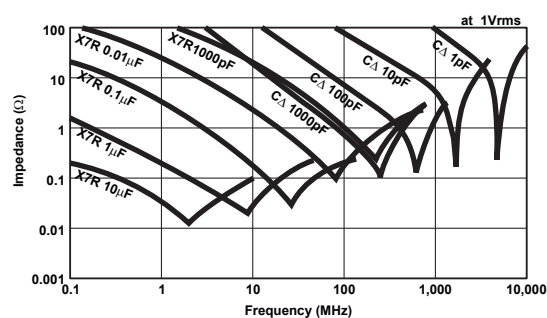
Aging
(change of capacitance over time)



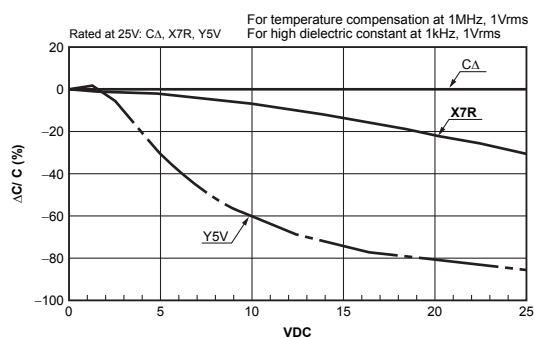
Capacitance-Temperature
(high dielectric constant)



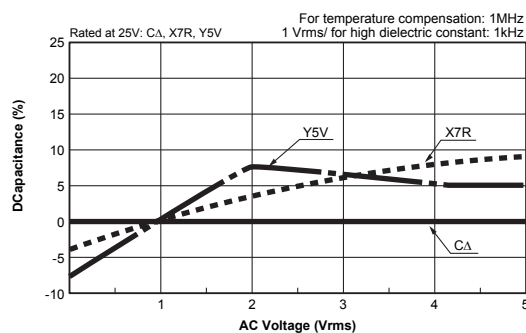
Impedance-Frequency



DC Bias



AC Voltage



Please verify individual characteristics at the design stage to ensure total suitability

Test Conditions and Specifications for Temperature Compensation type (C Δ to U Δ • SL Characteristics)

Test Items		Specifications (C: nominal capacitance)	Test Conditions		
Capacitance Value		Within tolerance	C $\leq$ 1000pF	1MHz $\pm$ 10%	0.5 to 5Vrms
Q		C $\geq$ 30pF: Q $\geq$ 1000 C $<$ 30pF: Q $\geq$ 400+20C	C $>$ 1000pF	1kHz $\pm$ 10%	
Insulation resistance (IR) (*5)		10,000M Ω or 500M Ω • μ F min., whichever is less	Measured after the rated voltage is applied for one minute at normal room temperature and humidity. (*3)		
Dielectric resistance (*5)		No problem observed	(*1) Apply 3 times of the rated voltage for 1 to 5 seconds.		
Appearance		No problem observed	Microscope (10 $\times$ magnification)		
Termination strength		No problem observed	Apply a sideward force of 500g (5N) (*2) to a PCB-mounted sample.		
Bending strength		No mechanical damage at 1mm bent	Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.		
Vibration test	Appearance	No significant change is detected	Vibration frequency: 10 to 55 (Hz) Amplitude: 1.5mm Sweeping condition: 10 $\rightarrow$ 55 $\rightarrow$ 10Hz/ min. In X, Y and Z directions: 2 hours each Total 6 hours		
	Δ C	Within tolerance			
	Q	C $\geq$ 30pF: Q $\geq$ 1000 C $<$ 30pF: Q $\geq$ 400+20C			
Soldering heat resistance	Appearance	No significant change is detected	Soak the sample in 260 $\pm$ 5 $^{\circ}$ C solder for 10 $\pm$ 0.5 seconds and place in a room at normal temperature and humidity; measure after 24 $\pm$ 2 hours. (Preheating Conditions)		
	Δ C	$\pm$ 2.5% or $\pm$ 0.25pF max., whichever is larger			
	Q	C $\geq$ 30pF: Q $\geq$ 1000 C $<$ 30pF: Q $\geq$ 400+20C			
	IR (*5)	10,000M Ω or 500M Ω • μ F min., whichever is smaller			
	Withstand voltage (*5)	Resists without problem			
Solderability		Ni/ Br termination: 90% min.	Soaking Condition		
			Sn63 Solder	235 $\pm$ 5 $^{\circ}$ C	2 $\pm$ 0.5 sec.
			Sn-3Ag-0.5Cu	245 $\pm$ 5 $^{\circ}$ C	3 $\pm$ 0.5 sec.
Temperature cycle	Appearance	No significant change is detected	(Cycle) Normal room temperature (3 min.) $\rightarrow$ Lowest operation temperature (30 min.) $\rightarrow$ Normal room temperature (3 min.) $\rightarrow$ Highest operation temperature (30 min.) $\rightarrow$ After five cycles, measure after 24 $\pm$ 2 hours.		
	Δ C	$\pm$ 2.5% or $\pm$ 0.25pF max., whichever is larger			
	Q	C $\geq$ 30pF: Q $\geq$ 1000 C $<$ 30pF: Q $\geq$ 400+20C			
	IR (*5)	10,000M Ω or 500M Ω • μ F min., whichever is smaller			
	Withstand voltage (*5)	Resists without problem			
Load humidity test (*4)	Appearance	No significant change is detected	After applying rated voltage for 500 $\pm$ 24/ -0 hours in pre-condition at 40 $\pm$ 2 $^{\circ}$ C, humidity 90 to 95%RH allow parts to stabilize for 48 $\pm$ 4 hours, at room temperature before making measurements.		
	Δ C	$\pm$ 7.5% or $\pm$ 0.75pF max., whichever is larger			
	Q	C $\geq$ 30pF: Q $\geq$ 200 C $<$ 30pF: Q $\geq$ 100+10C/ 3			
	IR (*5)	500M Ω or 25M Ω • μ F min., whichever is smaller			
High-temperature with loading	Appearance	No significant change is detected	After applying (*1) twice of the rated voltage at a temperature of 125 $\pm$ 3 $^{\circ}$ C for 1000 $\pm$ 48/ -0 hours, measure the sample after storing 24 $\pm$ 2 hours.		
	Δ C	$\pm$ 3% or $\pm$ 0.3pF max., whichever is larger			
	Q	C $\geq$ 30pF: Q $\geq$ 350 10pF $\leq$ C $<$ 30pF: Q $\geq$ 275+5C/ 2 C $<$ 10pF: Q $\geq$ 200+10C			
	IR (*5)	1,000M Ω or 50M Ω • μ F min., whichever is smaller			

*1 For the CF series, use 1.5 times when the rated voltage is 250V; use/ 1.2 times when the rated voltage exceeds 630V.

*2 2N at 0201 Size

*3 Apply 500V for 1 minute in case the rated voltage is 630V or higher.

*4 Except CF series.

*5 The charge and discharge current of the capacitor must not exceed 50mA.

Multilayer Ceramic Chip Capacitors

Test Conditions and Standards



Test Conditions and Specifications for High Dielectric Type (X5R, X7R, Y5V)

Test Items		Specifications		Test Conditions									
		X7R/ X5R	Y5V										
Capacitance Value		Within tolerance		Do previous treatment (*8, *14)									
tanδ (%)		2.5% max., 3.5% max. (*2), 7.0% max. (*12) 5.0% max. (*3), 7.5% max. (*17)	5.0% max., 7.0% max. (*13) 9.0% max. (*4), 12.5% max. (*5)	<table><tr><th>Capacitance</th><th>Fire</th><th>Vol</th></tr><tr><td>C≤10μF</td><td>1kHz±10%</td><td>1.0±0.2Vrms</td></tr><tr><td>C>10μF</td><td>120Hz±10%</td><td>0.5±0.1Vrms</td></tr></table>	Capacitance	Fire	Vol	C≤10μF	1kHz±10%	1.0±0.2Vrms	C>10μF	120Hz±10%	0.5±0.1Vrms
Capacitance	Fire	Vol											
C≤10μF	1kHz±10%	1.0±0.2Vrms											
C>10μF	120Hz±10%	0.5±0.1Vrms											
Insulation resistance (IR) (*15)		10,000MΩ or 500MΩ • μF min., whichever is less		Measured after the rated voltage is applied for 2 minutes at normal room temperature and humidity. (*10)									
Dielectric resistance (*15)		No problem observed		(*1) Apply 2.5 times of the rated voltage for 1 to 5 seconds.									
Appearance		No problem observed		Microscope (10×magnification)									
Termination strength (*6)		No problem observed		Apply a sideward force of 500g (5N) (*16) to a PCB-mounted sample.									
Bending strength test (*6)		No problem observed at 1mm bent		Glass epoxy PCB (*03, 05 type and CA Series: T=0.8mm); fulcrum Spacing: 90mm; for 10 seconds.									
Vibration test	Appearance	No significant change is detected		Vibration frequency: 10 to 55 (Hz)									
	ΔC	Within tolerance		Amplitude: 1.5mm									
	tanδ (%)	Satisfies the initial value		Sweeping condition: 10→55→10Hz/ min. In X, Y and Z directions: 2 hours each Total 6 hours									
Soldering heat resistance	Appearance	No significant change is detected		Do previous treatment (*8) Soak the sample in 260°C±5°C solder for 10±0.5 seconds and place in a room at normal temperature and humidity; measure after 48±4 hours. (Preheating Conditions)									
	ΔC	Within ±7.5%	Within ±20%	<table><tr><th>Order</th><th>Temperature</th><th>Time</th></tr><tr><td>1</td><td>80 to 100°C</td><td>2 minutes</td></tr><tr><td>2</td><td>150 to 200°C</td><td>2 minutes</td></tr></table>	Order	Temperature	Time	1	80 to 100°C	2 minutes	2	150 to 200°C	2 minutes
	Order	Temperature	Time										
	1	80 to 100°C	2 minutes										
	2	150 to 200°C	2 minutes										
tanδ (%)	Satisfies the initial value												
IR (*15)	10,000MΩ or 500MΩ • μF min., whichever is smaller												
	Withstand voltage (*15)	Resists without problem											
Solderability		Ni/ Br termination: 90% min.		Soaking Condition <table><tr><td>Sn63 Solder</td><td>235±5°C</td><td>2±0.5 sec.</td></tr><tr><td>Sn-3Ag-0.5Cu</td><td>245±5°C</td><td>3±0.5 sec.</td></tr></table>	Sn63 Solder	235±5°C	2±0.5 sec.	Sn-3Ag-0.5Cu	245±5°C	3±0.5 sec.			
Sn63 Solder	235±5°C	2±0.5 sec.											
Sn-3Ag-0.5Cu	245±5°C	3±0.5 sec.											
Temperature cycle	Appearance	No significant change is detected		Do previous treatment (*8) (Cycle)									
	ΔC	Within ±7.5%	Within ±20%	Normal room temperature (3 min.) →									
	tanδ (%)	Satisfies the initial value		Lowest operation temperature (30 min.) →									
	IR (*15)	10,000MΩ or 500MΩ • μF min., whichever is samller		Normal room temperature (3 min.) →									
	Withstand voltage (*15)	Resists without problem		Highest operation temperature (30 min.) →									
				After five cycles, measure after 48±4hours.									
Load humidity test (*11)	Appearance	No significant change is detected		Do previous treatment (*9)									
	ΔC	Within ±12.5%	Within ±30%	After applying rated voltage at 40±2°C and humidty 90 to 95%RH, for 500+24/ –0 hours and keep at room condition for 48±4 hours then measure and check the specification limits.									
	tanδ (%)	200% max. of initial value	150% max. of initial value										
	IR (*15)	500MΩ or 25MΩ • μF min., whichever is smaller											
High-temperature with loading	Appearance	No significant change is detected		Do previous treatment (*9)									
	ΔC	Within ±12.5%	Within ±30%	After applying twice (*7) of the rated voltage at the highest operating temperature for 1000+48/ –0 hours, measure the sample after storing 48±4 hours.									
	tanδ (%)	200% max. of initial value	150% max. of initial value										
	IR (*15)	1,000MΩ or 50MΩ • μF min., whichever is smaller											

*1 Use 1.5 times when the rated voltage is 250V or over.
Use 1.2 times when the rated voltage is 630V or over.

*2 X7R 16V/ 25V type.

*3 Apply to X5R16V/ 25V type, X7R 6.3V/ 10V type.

*4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).

*5 Apply to Y5V 6.3V/ 10V type. Apply 16% max. to CM21Y5V106/ CM316Y5V226.

*6 Exclude CT series with thickness of less than 0.66mm and CA series.

*7 Use 1.5 times when the rated voltage is 4V/ 6.3V/ 10V/ 250V and 100V (32X7R474/ 43X7R105/ 55X7R105).

Use 1.2 times when the rated voltage is 630V or over.

*8 Keep specimen at 150°C+0/-10°C for one hour, leave specimen at room ambient for 48±4 hours.

*9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours.

*10 For the CF series over 630V, apply 500V for 1 minutes at room ambient.

*11 Except CF series.

*12 Apply to X5R 10V type.

*13 Apply to 25V series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.

*14 Measurement condition 1kHz, 1Vrms for Y5V, C<47μF type.

*15 The charge/ discharge current of the capacitor must not exceed 50mA.

*16 2N at 0201 Size

*17 Apply to X5R 4V and 6.3V type.

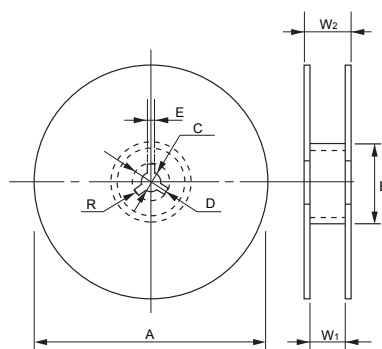
* The above test conditions and standards do not apply to products with optional specifications.

Multilayer Ceramic Chip Capacitors Packaging Options



Tape and Reel

• Reel



Reel

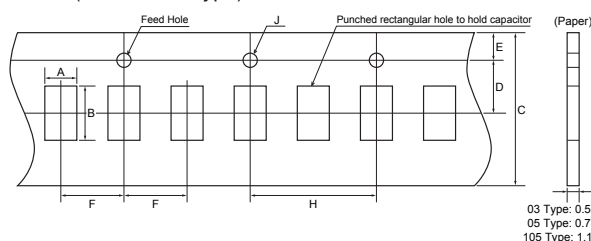
(Unit: mm)

Code Reel	A	B	C	D
7-inch Reel (CODE: T, H)	180 ⁺⁰ _{-2.0}	φ60 min.	13±0.5	21±0.8
13-inch Reel (CODE: L, N)	330±2.0	φ100±1.0		
Code Reel	E	W ₁	W ₂	R
7-inch Reel (CODE: T, H)	2.0±0.5	10.0±1.5	16.5 max.	1.0
13-inch Reel (CODE: L, N)		9.5±1.0		

* Carrier tape width 8mm.

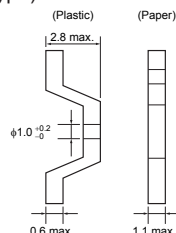
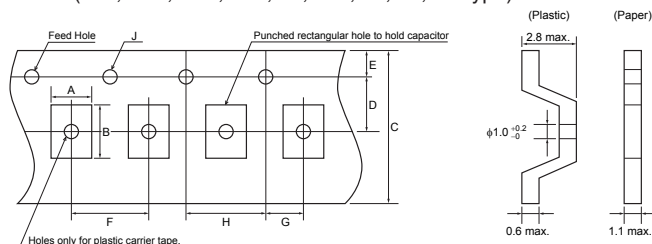
For size 42 (1808) or over, Tape width 12mm and W₁: 14±1.5, W₂: 18.4mm max.

F=2mm (03, 05, 105 Type)

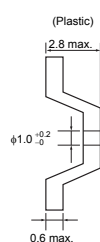
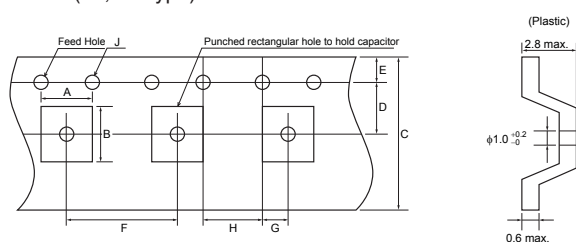


03 Type: 0.5 max.
05 Type: 0.75 max.
105 Type: 1.1 max.

F=4mm (105, D11, D12, F12, 21, 316, 32, 42, 52 Type)

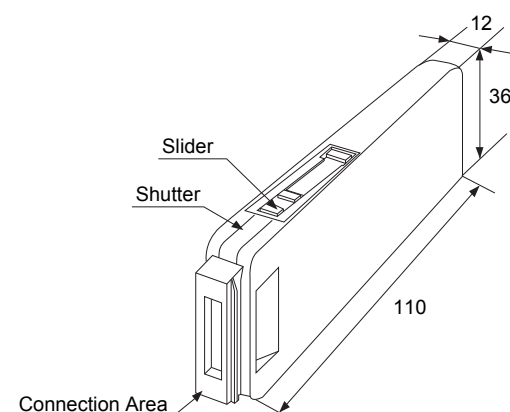


F=8mm (43, 55 Type)



Bulk Cassette

(Unit: mm)



Carrier Tape

(Unit: mm)

Type	A	B	F
03 (0.6×0.3)	0.37±0.03	0.67±0.03	2.0±0.05
05 (1.0×0.5)	0.65±0.1	1.15±0.1	2.0±0.05
105 (1.6×0.8)	1.0±0.2	1.8±0.2	4.0±0.1
D11 (1.37×1.0)	1.15±0.1	1.55±0.1	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
21 (2.0×1.25)	1.5±0.2	2.3±0.2	4.0±0.1
316 (3.2×1.6)	2.0±0.2	3.6±0.2	4.0±0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4±0.2	6.0±0.2	4.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0±0.1

(Unit: mm)

F	Carrier Tape	C	D	E	G	H	J
2.0 ±0.05	8mm Paper	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 +0.1/-0
4.0 ±0.1	8mm Plastic						
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				

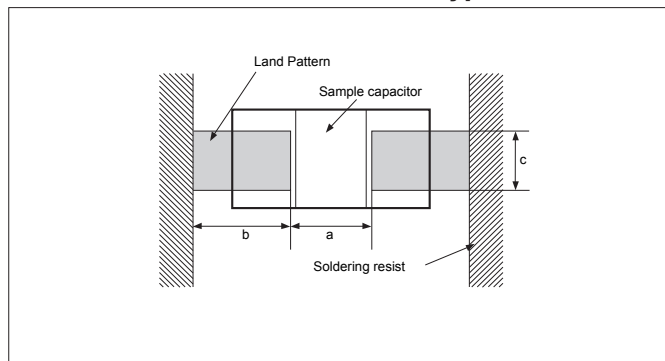
Circuit Design

1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.
Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur. The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.
When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage. Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.
8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
9. Please contact us upon using conductive adhesives.

Storage

1. If the component is stored in minimal packaging (a heat-sealed or chuck-type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.
5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
6. Chip capacitors may crack if exposed to hydrogen (H₂) gas while sealed or if coated with silicon, which generates hydrogen gas.

Dimensions for recommended typical land



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

- The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
- In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist.

Standard

(Unit: mm)

Size	L×W	a	b	c
03	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42	4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43	4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
55	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

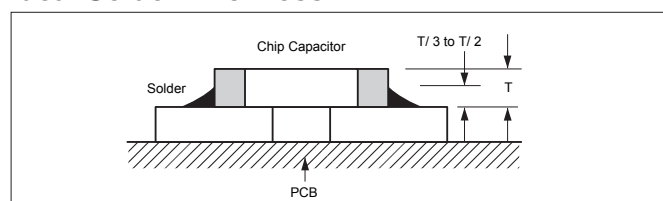
* CA series: Please refer applicable page.

Automotive Series

(Unit: mm)

Size	L×W	a	b	c
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

Ideal Solder Thickness



Typical mounting problems

Item	Not recommended example	Recommended example/ Separated by solder
Multiple parts mount		
Mount with leaded parts		
Wire soldering after mounting		
Overview		

Mounting Design

The chip could crack if the PCB warps during processing after the chip has been soldered.

Recommended chip position on PCB to minimize stress from PCB warpage



Actual Mounting

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
- 3) To minimize the shock of the vacuum nozzle, provide a support pin on the back of the PCB to minimize PCB flexure.



- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

Resin Mold

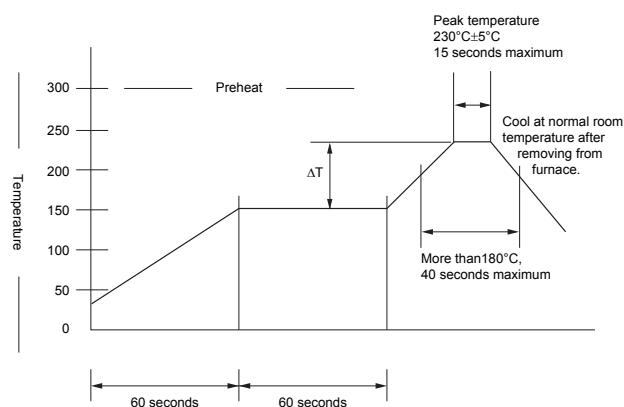
- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

Soldering Method

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
- 2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.

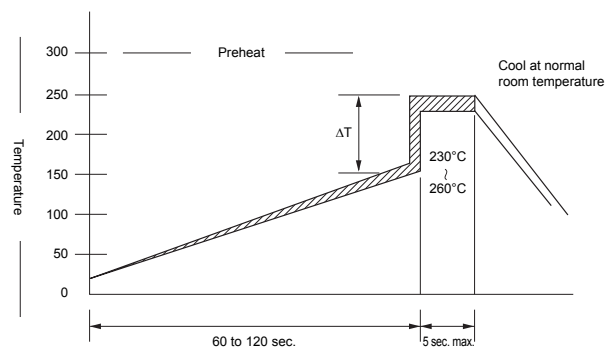
Recommended Temperature Profile (62Sn Solder)

Reflow



- ① Minimize soldering time.
- ② Ensure that allowable temperature difference does not exceed 150°C.
- ③ Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger.

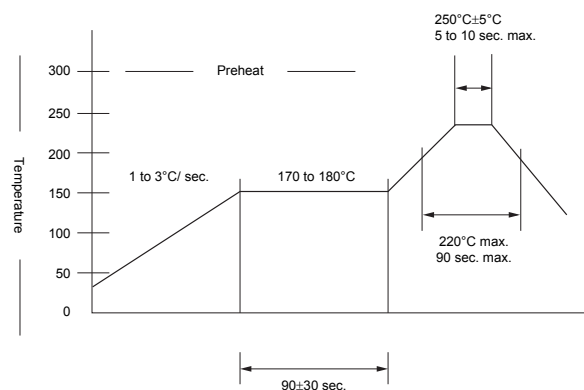
Wave



- ① Ensure that the chip capacitor is preheated adequately.
- ② Ensure that the temperature difference (ΔT) does not exceed 150°C.
- ③ Cool naturally after soldering.
- ④ Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger.

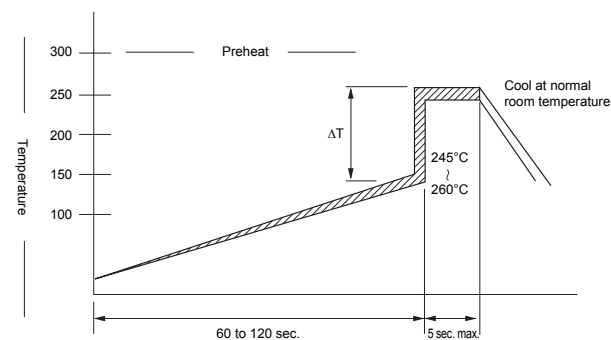
Recommended Temperature Profile (Sn-3Ag-0.5Cu)

Reflow



- ① Minimize soldering time.
- ② Ensure that allowable temperature difference does not exceed 150°C.
- ③ Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger.

Wave



- ① Ensure that the chip capacitor is preheated adequately.
- ② Ensure that the temperature difference (ΔT) does not exceed 150°C.
- ③ Cool naturally after soldering.
- ④ Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger.

Soldering iron

- 1) Temperature of iron chip 380°C max.
- 2) Wattage 80W max.
- 3) Tip shape of soldering iron ϕ 3.0mm max.
- 4) Soldering Time 3 sec. max.

5) Cautions

- a) Pre-heating is necessary Rapid heating must be avoided.
Delta T ≤ 150°C
- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.